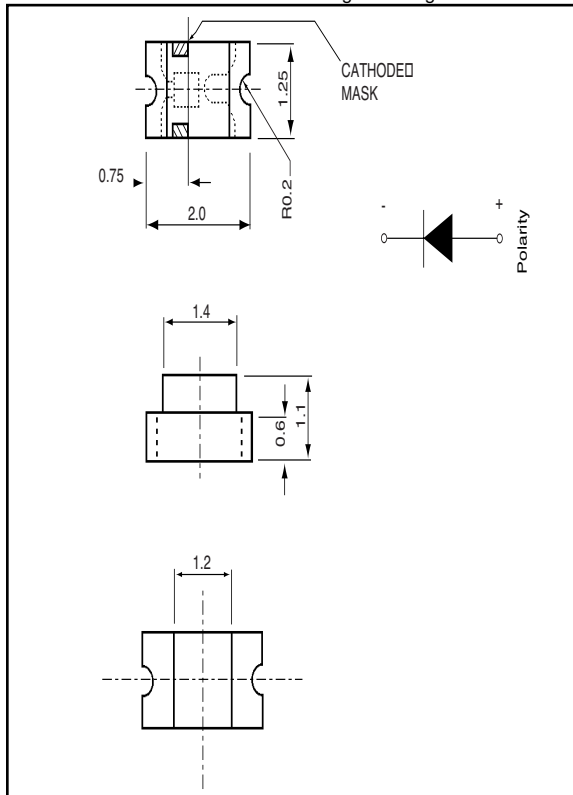




Weight: 2.0 mg Unit: mm

Product specifications contained herein may be changed without prior notice. It is therefore advisable to contact Purdy Electronics before proceeding with the design of equipment incorporating this product.



# AND4SA

## GaAsP Bright Red Light Emission Surface Mount Package

### Features

- Small package size
- 2.0 (l) x 1.25 (w) x 1.1 (h) size
- Suitable for REFLOW soldering
- Recommended Forward Current: 10 mA
- RoHS Compliant

### Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

Characteristics	Symbol	Rating	Unit
Forward Current	$I_F$	25	mA
Reverse Voltage	$V_R$	4	V
Power Dissipation	$P_D$	62.5	mW
Operating Temperature Range	$T_{Opr}$	-30 to 85	$^\circ\text{C}$
Storage Temperature Range	$T_{Sig}$	-30 to 90	$^\circ\text{C}$

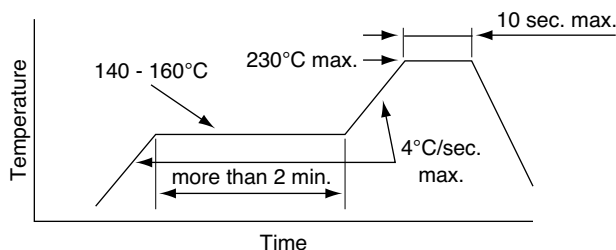
### Electro-Optical Characteristics ( $T_a = 25^\circ\text{C}$ )

Characteristics	Symbol	Test Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	$V_F$	$I_F = 20 \text{ mA}$	–	2.0	2.8	V
Reverse Current	$I_R$	$V_R = 4 \text{ V}$	–	–	100	$\mu\text{A}$
Luminous Intensity	$I_V$	$I_F = 20 \text{ mA}$	5	9	–	mcd
Peak Emission Wavelength	$\lambda_P$	$I_F = 20 \text{ mA}$	–	640	–	nm
Spectral Line Half Width	$\Delta\lambda$	$I_F = 20 \text{ mA}$	–	20	–	nm
Dominant Wavelength	$\lambda_d$	$I_F = 20 \text{ mA}$	–	635	–	nm
Full Viewing Angle	$\theta$	$I_V = 1/2 \text{ Peak}$	–	140	–	degree

### Precaution

Please be careful of the following:

1. Manual soldering: maximum temperature of iron tip: 260 $^\circ\text{C}$  max.  
Soldering time: within 5 sec. per solder-land  
Soldering portion of lead: up to 1.6 mm from the body of the device
2. Reflow solder: recommended condition is as follows:



The following soldering patterns are recommended for reflow

